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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

# Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

# Details

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I <sup>2</sup> C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc64at-04-l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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# FIGURE 4-17: PIR1 REGISTER FOR PIC16C63/R63/66 (ADDRESS 0Ch)

_	_	RCIF	TXIF	SSPIF	CCP1IF	TMB2IF	TMR1IF	B = Beadable	hit
bit7		1101					bit0	W = Writable U = Unimpler read as ' - n = Value at	bit nented bit, 0'
bit 7-6:	Reserved:	Always ma	intain thes	e bits clear.					
bit 5:	<b>RCIF:</b> USA 1 = The US 0 = The US	ART receiv	e buffer is	full (cleared	I by reading	RCREG)			
bit 4:	<b>TXIF:</b> USA 1 = The US 0 = The US	ART transr	nit buffer is	empty (cle	ared by writi	ng to TXRE	G)		
bit 3:	<b>SSPIF</b> : Syr 1 = The tra 0 = Waiting	nsmission/ı	eception is		ag bit must be clea	ared in softw	vare)		
bit 2:	0 = No TMI Compare M	ode 1 register c R1 register <u>Mode</u> 1 register c R1 register 2	apture occi capture oc ompare ma	curred	be cleared i ed (must be c red	,	ftware)		
bit 1:	<b>TMR2IF</b> : T 1 = TMR2 t 0 = No TM	o PR2 mat	ch occurred	d (must be o	bit cleared in so	ftware)			
bit 0:	<b>TMR1IF</b> : T 1 = TMR1 1 0 = No TMI	register ove	rflow occur	red (must b	e cleared in	software)			
globa	0 = No TMI	R1 register	overflow or	curred	n occurs rega	ardless of th		corresponding e rupt flag bits are	

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# FIGURE 4-19: PIR1 REGISTER FOR PIC16C65/65A/R65/67 (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0						
PSPIF bit7	—	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF bit0	<ul> <li>R = Readable bit</li> <li>W = Writable bit</li> <li>U = Unimplemented bit, read as '0'</li> <li>n = Value at POR reset</li> </ul>					
bit 7:		or a write o	peration ha	as taken pla	ace (must be ce	cleared in s	oftware)						
bit 6:	Reserved:	0 = No read or write operation has taken place Reserved: Always maintain this bit clear.											
bit 5:	<b>RCIF:</b> USA 1 = The US 0 = The US	SART receiv	/e buffer is	full (cleared	d by reading	RCREG)							
bit 4:	<b>TXIF:</b> USA 1 = The US 0 = The US	SART trans	nit buffer is	empty (cle	eared by writ	ing to TXRE	EG)						
bit 3:		nsmission/	reception is		ag bit (must be clea	ared in softw	vare)						
bit 2:	0 = Waiting to transmit/receive CCP1IF: CCP1 Interrupt Flag bit <u>Capture Mode</u> 1 = A TMR1 register capture occurred (must be cleared in software) 0 = No TMR1 register capture occurred <u>Compare Mode</u> 1 = A TMR1 register compare match occurred (must be cleared in software) 0 = No TMR1 register compare match occurred <u>PWM Mode</u> Unused in this mode												
bit 1:	<b>TMR2IF</b> : T 1 = TMR2 t 0 = No TMI	to PR2 mat	ch occurred	d (must be	bit cleared in so	ftware)							
bit 0:	<b>TMR1IF</b> : T 1 = TMR1 1 0 = No TMI	register ove	rflow occur	red (must b	be cleared in	software)							
global		GIE (INTC						corresponding enable bit or the rupt flag bits are clear prior to					

# TABLE 5-1: PORTA FUNCTIONS

Name	Bit#	Buffer Type	Function
RA0	bit0	TTL	Input/output
RA1	bit1	TTL	Input/output
RA2	bit2	TTL	Input/output
RA3	bit3	TTL	Input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for Timer0. Output is open drain type.
RA5/SS (1)	bit5	TTL	Input/output or slave select input for synchronous serial port.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: The PIC16C61 does not have PORTA<5> or TRISA<5>, read as '0'.

# TABLE 5-2: REGISTERS/BITS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
05h	PORTA	—	—	RA5 <sup>(1)</sup>	RA5 <sup>(1)</sup> RA4 RA3 RA2 RA1 RA0						uu uuuu
85h	TRISA	—	—	PORTA Data Direction Register <sup>(1)</sup>						11 1111	11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

Note 1: PORTA<5> and TRISA<5> are not implemented on the PIC16C61, read as '0'.

# 5.3 PORTC and TRISC Register

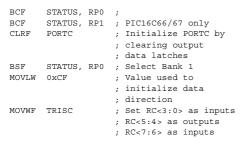
### Applicable Devices

### 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

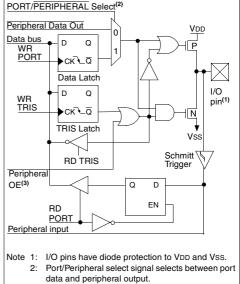
PORTC is an 8-bit wide bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modifywrite instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

### EXAMPLE 5-3: INITIALIZING PORTC



# FIGURE 5-6: PORTC BLOCK DIAGRAM



3: Peripheral OE (output enable) is only activated if peripheral select is active.

# TABLE 5-5: PORTC FUNCTIONS FOR PIC16C62/64

Name	Bit#	Buffer Type	Function
RC0/T1OSI/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator input or Timer1 clock input
RC1/T1OSO	bit1	ST	Input/output port pin or Timer1 oscillator output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and $I^2C$ modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O ( $I^2C$ mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

# 5.7 Parallel Slave Port

#### Applicable Devices

### 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTD operates as an 8-bit wide parallel slave port (microprocessor port) when control bit PSPMODE (TRISE<4>) is set. In slave mode it is asynchronously readable and writable by the external world through  $\overline{\text{RD}}$  control input (RE0/ $\overline{\text{RD}}$ ) and  $\overline{\text{WR}}$  control input pin (RE1/ $\overline{\text{WR}}$ ).

It can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting PSPMODE enables port pin RE0/RD to be the RD input, RE1/WR to be the WR input and RE2/CS to be the CS (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (set).

There are actually two 8-bit latches, one for data-out (from the PIC16/17) and one for data input. The user writes 8-bit data to PORTD data latch and reads data from the port pin latch (note that they have the same address). In this mode, the TRISD register is ignored since the microprocessor is controlling the direction of data flow.

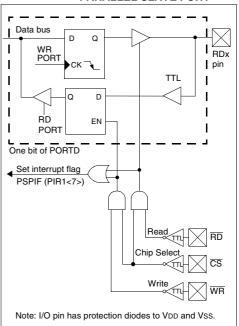
A write to the PSP occurs when both the  $\overline{CS}$  and  $\overline{WR}$  lines are first detected low. When either the  $\overline{CS}$  or  $\overline{WR}$  lines become high (level triggered), then the Input Buffer Full status flag bit IBF (TRISE<7>) is set on the Q4 clock cycle, following the next Q2 cycle, to signal the write is complete (Figure 5-12). The interrupt flag bit PSPIF (PIR1<7>) is also set on the same Q4 clock cycle. IBF can only be cleared by reading the PORTD input latch. The input Buffer Overflow status flag bit IBOV (TRISE<5>) is set if a second write to the Parallel Slave Port is attempted when the previous byte has not been read out of the buffer.

A read from the PSP occurs when both the  $\overline{CS}$  and  $\overline{RD}$  lines are first detected low. The Output Buffer Full status flag bit OBF (TRISE<6>) is cleared immediately (Figure 5-13) indicating that the PORTD latch is waiting to be read by the external bus. When either the  $\overline{CS}$  or  $\overline{RD}$  pin becomes high (level triggered), the interrupt flag bit PSPIF is set on the Q4 clock cycle, following the next Q2 cycle, indicating that the read is complete. OBF remains low until data is written to PORTD by the user firmware.

When not in Parallel Slave Port mode, the IBF and OBF bits are held clear. However, if flag bit IBOV was previously set, it must be cleared in firmware.

An interrupt is generated and latched into flag bit PSPIF when a read or write operation is completed. PSPIF must be cleared by the user in firmware and the interrupt can be disabled by clearing the interrupt enable bit PSPIE (PIE1<7>).

### FIGURE 5-11: PORTD AND PORTE AS A PARALLEL SLAVE PORT



### 11.4.4 MULTI-MASTER

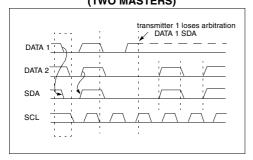
PIC16C6X

The  $I^2C$  protocol allows a system to have more than one master. This is called multi-master. When two or more masters try to transfer data at the same time, arbitration and synchronization occur.

### 11.4.4.1 ARBITRATION

Arbitration takes place on the SDA line, while the SCL line is high. The master which transmits a high when the other master transmits a low loses arbitration (Figure 11-22), and turns off its data output stage. A master which lost arbitration can generate clock pulses until the end of the data byte where it lost arbitration. When the master devices are addressing the same device, arbitration continues into the data.

### FIGURE 11-22: MULTI-MASTER ARBITRATION (TWO MASTERS)



Masters that also incorporate the slave function, and have lost arbitration must immediately switch over to slave-receiver mode. This is because the winning master-transmitter may be addressing it.

Arbitration is not allowed between:

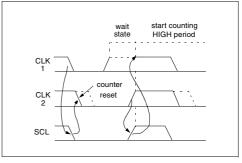
- A repeated START condition
- · A STOP condition and a data bit
- A repeated START condition and a STOP condition

Care needs to be taken to ensure that these conditions do not occur.

#### 11.2.4.2 Clock Synchronization

Clock synchronization occurs after the devices have started arbitration. This is performed using a wired-AND connection to the SCL line. A high to low transition on the SCL line causes the concerned devices to start counting off their low period. Once a device clock has gone low, it will hold the SCL line low until its SCL high state is reached. The low to high transition of this clock may not change the state of the SCL line, if another device clock is still within its low period. The SCL line is held low by the device with the longest low period. Devices with shorter low periods enter a high waitstate, until the SCL line comes high. When the SCL line comes high, all devices start counting off their high periods. The first device to complete its high period will pull the SCL line low. The SCL line high time is determined by the device with the shortest high period, Figure 11-23.

### FIGURE 11-23: CLOCK SYNCHRONIZATION



### 11.5.1 SLAVE MODE

PIC16C6X

In slave mode, the SCL and SDA pins must be configured as inputs (TRISC<4:3> set). The SSP module will override the input state with the output data when required (slave-transmitter).

When an address is matched or the data transfer after an address match is received, the hardware automatically will generate the acknowledge ( $\overline{ACK}$ ) pulse, and then load the SSPBUF register with the received value currently in the SSPSR register.

There are certain conditions that will cause the SSP module not to give this ACK pulse. These are if either (or both):

- a) The buffer full bit BF (SSPSTAT<0>) was set before the transfer was received.
- b) The overflow bit SSPOV (SSPCON<6>) was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF (PIR1<3>) is set. Table 11-4 shows what happens when a data transfer byte is received, given the status of bits BF and SSPOV. The shaded cells show the condition where user software did not properly clear the overflow condition. Flag bit BF is cleared by reading the SSPBUF register while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the  $I^2C$  specification as well as the requirement of the SSP module is shown in timing parameter #100 and parameter #101.

#### 11.5.1.1 ADDRESSING

Once the SSP module has been enabled, it waits for a START condition to occur. Following the START condition, the 8-bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The

address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match, and the BF and SSPOV bits are clear, the following events occur:

- a) The SSPSR register value is loaded into the SSPBUF register.
- b) The buffer full bit, BF is set.
- c) An ACK pulse is generated.
- d) SSP interrupt flag bit, SSPIF (PIR1<3>) is set (interrupt is generated if enabled) - on the falling edge of the ninth SCL pulse.

In 10-bit address mode, two address bytes need to be received by the slave (Figure 11-16). The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit  $R/\overline{W}$  (SSPSTAT-2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address the first byte would equal '1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address. The sequence of events for 10-bit address is as follows, with steps 7-9 for slave-transmitter:

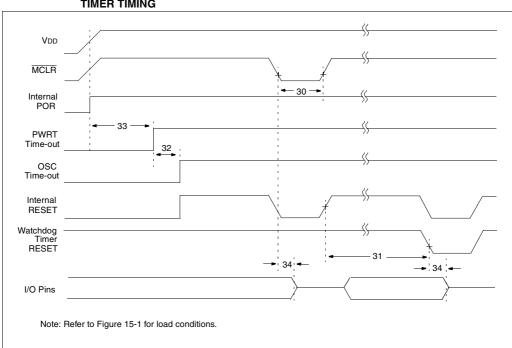
- 1. Receive first (high) byte of Address (bits SSPIF, BF, and bit UA (SSPSTAT<1>) are set).
- Update the SSPADD register with second (low) byte of Address (clears bit UA and releases the SCL line).
- 3. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 4. Receive second (low) byte of Address (bits SSPIF, BF, and UA are set).
- Update the SSPADD register with the first (high) byte of Address, if match releases SCL line, this will clear bit UA.
- 6. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 7. Receive repeated START condition.
- 8. Receive first (high) byte of Address (bits SSPIF and BF are set).
- 9. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.

### TABLE 11-4: DATA TRANSFER RECEIVED BYTE ACTIONS

	ts as Data s Received			Set bit SSPIF	
BF	SSPOV	$SSPSR \to SSPBUF$	Generate ACK Pulse	(SSP Interrupt occurs if enabled)	
0	0	Yes	Yes	Yes	
1	0	No	No	Yes	
1	1	No	No	Yes	
0	1	No	No	Yes	

Q2	Q3Q4	Q1 Q2 Q3 Q	4Q1Q2	Q3Q4Q1Q2	03040102	03040102	03040102	03 04 01 02 0	30401020	30401020	30401020304
C7/RX/DT pin	1		bit0	bit1	bit2	bit3	bit4	, bit5	bit6	bit7	1
C6/TX/CK pin –	1 1 1	Γ								<u> </u>	1
Write to bit SREN			1 1 1	1 1 1 1				, , , , ,	1 1 1 1		
SREN bit -			1	1 1 1			1	1	1		1
CREN bit	'0'		t t	1 1 1	1	1	1	1	1 1	1	'0'
RCIF bit (interrupt) <sup></sup>			t t t	1 1 1 1	1 1 1	1 1 1	1 1 1	1 1 1 1	1 1 1 1	1 1 1 1	
Read RXREG -	1 1 1		1 1 1	1 1 1	1 1 1	1	1 1 1	1 1 1	1 1 1	1 1 1	

# FIGURE 12-14: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



# FIGURE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

# TABLE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30*	TmcL	MCLR Pulse Width (low)	200	—	—	ns	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period		1024Tosc	—		TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34*	Tioz	I/O Hi-impedance from MCLR Low		—	100	ns	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

# 17.1 DC Characteristics: PIC16C62/64-04 (Commercial, Industrial) PIC16C62/64-10 (Commercial, Industrial) PIC16C62/64-20 (Commercial, Industrial)

DC CHAR		Standard Operating Conditions (unless otherwise stated)           Operating temperature $-40^{\circ}$ C $\leq$ TA $\leq$ $+85^{\circ}$ C for industrial and           0°C $\leq$ TA $\leq$ $+70^{\circ}$ C for commercial							
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions		
D001 D001A	Supply Voltage	Vdd	4.0 4.5	-	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration		
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V			
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details		
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details		
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5.0	mA	XT, RC, osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)		
D013			-	13.5	30	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V		
D020 D021 D021A	Power-down Current (Note 3, 5)	IPD	- - -	10.5 1.5 1.5	42 21 24	μΑ μΑ μΑ	$ \begin{array}{l} V\text{DD}=4.0V, WDT \mbox{ enabled}, -40^\circ C \mbox{ to } +85^\circ C \\ V\text{DD}=4.0V, WDT \mbox{ disabled}, -0^\circ C \mbox{ to } +70^\circ C \\ V\text{DD}=4.0V, WDT \mbox{ disabled}, -40^\circ C \mbox{ to } +85^\circ C \end{array} $		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

 $\overline{MCLR} = VDD$ ; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.

- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

DC CHA	RACTERISTICS	Standard Operating Conditions (unless otherwise stated)Operating temperature $-40^{\circ}$ C $\leq$ TA $\leq$ +85°C for industrial and $0^{\circ}$ C $\leq$ TA $\leq$ +70°C for commercialOperating voltage VDD range as described in DC spec Section 17.1and Section 17.2							
Param No.	Characteristic	Sym	Min	Тур †	Max	Units	Conditions		
D100	Capacitive Loading Specs on Output Pins OSC2 pin	Cosc2	-	-	15		In XT, HS and LP modes when external clock is used to drive OSC1.		
D101 D102	All I/O pins and OSC2 (in RC mode) SCL, SDA in I <sup>2</sup> C mode	Cio Cb	-	-	50 400	pF pF			

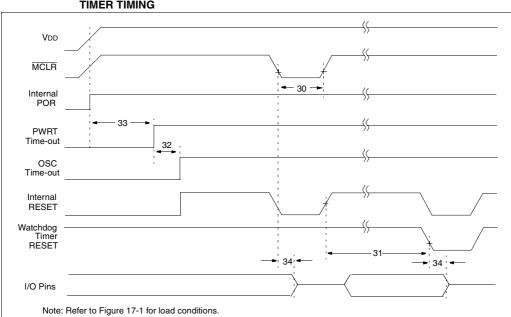
\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.



# FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

# TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

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31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	-	1024Tosc	_	-	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34*	Tioz	I/O Hi-impedance from MCLR Low	-	—	100	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

## 20.2 DC Characteristics: PIC16LC63/65A-04 (Commercial, Industrial)

DC CHARACTERISTICSStandard Operating Conditions (unless otherwise stated)Operating temperature $-40^{\circ}$ C $\leq Ta \leq +85^{\circ}$ C for industrial and $0^{\circ}$ C $\leq Ta \leq +70^{\circ}$ C for commercial								
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions	
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)	
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V		
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details	
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details	
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled	
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)	
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
D015*	Brown-out Reset Current (Note 6)	$\Delta$ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V	
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C	
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C	
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C	
D023*	Brown-out Reset Current (Note 6)	$\Delta$ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

- $\overline{MCLR} = VDD$ ; WDT enabled/disabled as specified.
- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

# PIC16C6X

# Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

# FIGURE 20-3: CLKOUT AND I/O TIMING

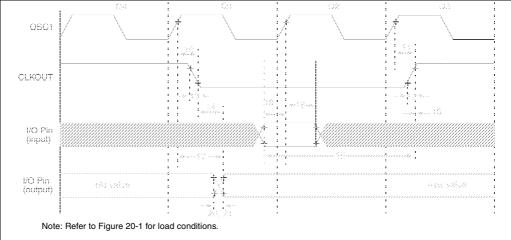


TABLE 20-3:	CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	_	75	200	ns	Note 1	
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		_	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT $\downarrow$ to Port out valid		_	_	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	Tosc + 200	_	-	ns	Note 1	
16*	TckH2iol	Port in hold after CLKOUT $\uparrow$	0	_	_	ns	Note 1	
17*	TosH2ioV	OSC1 <sup>↑</sup> (Q1 cycle) to Port out val	_	50	150	ns		
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input	PIC16 <b>C</b> 63/65A	100	_	_	ns	
		invalid (I/O in hold time)	PIC16LC63/65A	200	_	_	ns	
19*	TioV2osH	Port input valid to OSC1 <sup>↑</sup> (I/O in	setup time)	0	_	_	ns	
20*	TioR	Port output rise time	PIC16 <b>C</b> 63/65A	_	10	40	ns	
			PIC16LC63/65A	_	_	80	ns	
21*	TioF	Port output fall time	PIC16 <b>C</b> 63/65A	_	10	40	ns	
		PIC16 <b>LC</b> 63/65/		_	_	80	ns	
22††*	Tinp	INT pin high or low time	1	Тсү	_	_	ns	
23††*	Trbp	RB7:RB4 change INT high or low	/ time	Тсү	—	_	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

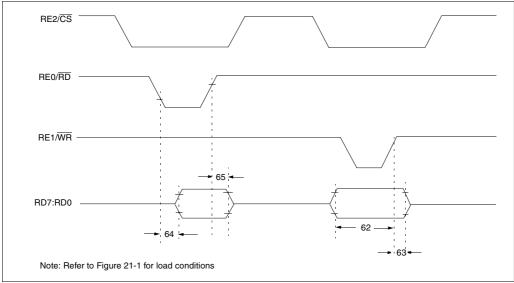
tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

# FIGURE 21-8: PARALLEL SLAVE PORT TIMING (PIC16CR65)

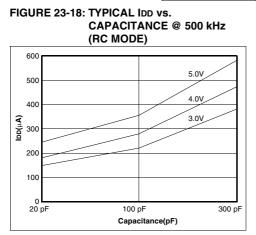


# TABLE 21-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16CR65)

Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
TdtV2wrH	Data in valid before $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ (setup time)		20	_	_	ns	
TwrH2dtI $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ to data–in invalid (hold		PIC16 <b>CR</b> 65	20	_	—	ns	
t	time)	PIC16 <b>LCR</b> 65	35	—	—	ns	
TrdL2dtV	$\overline{\text{RD}}\downarrow$ and $\overline{\text{CS}}\downarrow$ to data–out valid		-	—	80	ns	
TrdH2dtl	$\overline{\text{RD}}$ for $\overline{\text{CS}}$ to data-out invalid		10	—	30	ns	
	TdtV2wrH TwrH2dtl TrdL2dtV	TdtV2wrH     Data in valid before WR↑ or CS↑ (setu       TwrH2dtl     WR↑ or CS↑ to data–in invalid (hold time)       TrdL2dtV     RD↓ and CS↓ to data–out valid	TdtV2wrH     Data in valid before WR↑ or CS↑ (setup time)       TwrH2dtl     WR↑ or CS↑ to data-in invalid (hold time)       PIC16CR65       PIC16LCR65       TrdL2dtV     RD↓ and CS↓ to data-out valid	TdtV2wrH     Data in valid before WR↑ or CS↑ (setup time)     20       TwrH2dtl     WR↑ or CS↑ to data-in invalid (hold time)     PIC16CR65     20       TrdL2dtV     RD↓ and CS↓ to data-out valid	TdtV2wrH     Data in valid before $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ (setup time)     20        TwrH2dtl $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ to data-in invalid (hold time)     PIC16 <b>CR</b> 65     20        TrdL2dtV $\overline{RD}^{\downarrow}$ and $\overline{CS}^{\downarrow}$ to data-out valid	TdtV2wrH     Data in valid before $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ (seture time)     20        TwrH2dtl $\overline{WR}^{\uparrow}$ or $\overline{CS}^{\uparrow}$ to data-in invalid (hold time)     PIC16 <b>CR</b> 65     20        TrdL2dtV $\overline{RD}_{\downarrow}$ and $\overline{CS}_{\downarrow}$ to data-out valid      80	TdtV2wrH       Data in valid before $\overline{WR}$ or $\overline{CS}$ (setup time)       20        ns         TwrH2dtl $\overline{WR}$ or $\overline{CS}$ to data-in invalid (hold time)       PIC16 <b>CR</b> 65       20        ns         TrdL2dtV $\overline{RD}$ and $\overline{CS}$ to data-out valid        ns       ns         TrdL2dtV $\overline{RD}$ and $\overline{CS}$ to data-out valid         ns

These parameters are characterized but not tested.

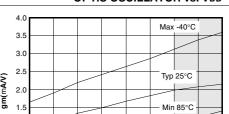
t Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.



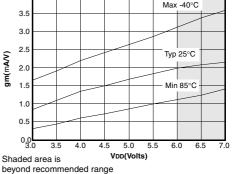
#### **TABLE 23-1: RC OSCILLATOR** FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C				
Cext	nexi					
22 pF	5k	4.12 MHz	± 1.4%			
	10k	2.35 MHz	± 1.4%			
	100k	268 kHz	± 1.1%			
100 pF	3.3k	1.80 MHz	± 1.0%			
	5k	1.27 MHz	± 1.0%			
	10k	688 kHz	± 1.2%			
	100k	77.2 kHz	± 1.0%			
300 pF	3.3k	707 kHz	± 1.4%			
	5k	501 kHz	± 1.2%			
	10k	269 kHz	± 1.6%			
	100k	28.3 kHz	± 1.1%			

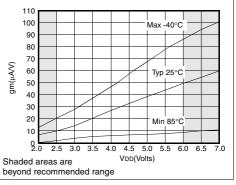
The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.



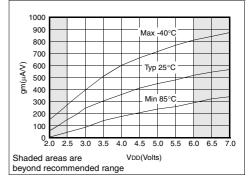
# FIGURE 23-19: TRANSCONDUCTANCE(gm) OF HS OSCILLATOR vs. VDD



# FIGURE 23-20: TRANSCONDUCTANCE(gm) OF LP OSCILLATOR vs. VDD



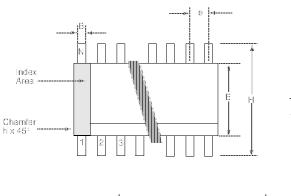
# FIGURE 23-21: TRANSCONDUCTANCE(gm) OF XT OSCILLATOR vs. VDD

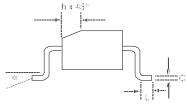


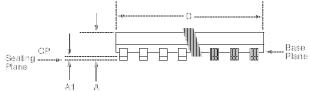
Data based on matrix samples. See first page of this section for details.

# 24.4 18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



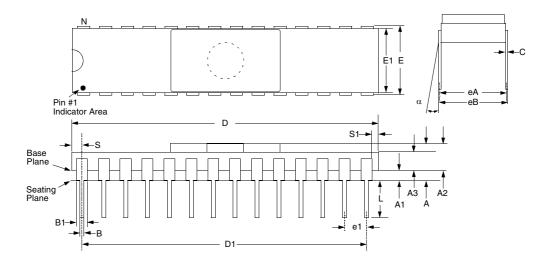




	Package Group: Plastic SOIC (SO)									
		Millimeters		Inches						
Symbol	Min	Max	Notes	Min	Max	Notes				
α	0°	8°		0°	8°					
А	2.362	2.642		0.093	0.104					
A1	0.101	0.300		0.004	0.012					
В	0.355	0.483		0.014	0.019					
С	0.241	0.318		0.009	0.013					
D	11.353	11.735		0.447	0.462					
E	7.416	7.595		0.292	0.299					
е	1.270	1.270	Reference	0.050	0.050	Reference				
Н	10.007	10.643		0.394	0.419					
h	0.381	0.762		0.015	0.030					
L	0.406	1.143		0.016	0.045					
N	18	18		18	18					
CP	_	0.102		-	0.004					

# 24.9 28-Lead Ceramic Side Brazed Dual In-Line with Window (300 mil) (JW)

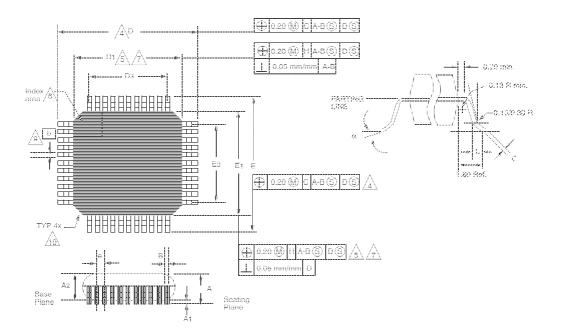
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Ceramic Side Brazed Dual In-Line (CER)									
0 militad		Millimeters		Inches					
Symbol	Min	Мах	Notes	Min	Max	Notes			
α	0°	10°		0°	10°				
Α	3.937	5.030		0.155	0.198				
A1	1.016	1.524		0.040	0.060				
A2	2.921	3.506		0.115	0.138				
A3	1.930	2.388		0.076	0.094				
В	0.406	0.508		0.016	0.020				
B1	1.219	1.321	Typical	0.048	0.052				
С	0.228	0.305	Typical	0.009	0.012				
D	35.204	35.916		1.386	1.414				
D1	32.893	33.147	Reference	1.295	1.305				
E	7.620	8.128		0.300	0.320				
E1	7.366	7.620		0.290	0.300				
e1	2.413	2.667	Typical	0.095	0.105				
eA	7.366	7.874	Reference	0.290	0.310				
eB	7.594	8.179		0.299	0.322				
L	3.302	4.064		0.130	0.160				
Ν	28	28		28	28				
S	1.143	1.397		0.045	0.055				
S1	0.533	0.737		0.021	0.029				

## 24.12 44-Lead Plastic Surface Mount (MQFP 10x10 mm Body 1.6/0.15 mm Lead Form) (PQ)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Package Group: Plastic MQFP									
		Millimeters		Inches						
Symbol	Min	Max	Notes	Min	Max	Notes				
α	0°	<b>7</b> °		0°	<b>7</b> °					
А	2.000	2.350		0.078	0.093					
A1	0.050	0.250		0.002	0.010					
A2	1.950	2.100		0.768	0.083					
b	0.300	0.450	Typical	0.011	0.018	Typical				
С	0.150	0.180		0.006	0.007					
D	12.950	13.450		0.510	0.530					
D1	9.900	10.100		0.390	0.398					
D3	8.000	8.000	Reference	0.315	0.315	Reference				
E	12.950	13.450		0.510	0.530					
E1	9.900	10.100		0.390	0.398					
E3	8.000	8.000	Reference	0.315	0.315	Reference				
е	0.800	0.800		0.031	0.032					
L	0.730	1.030		0.028	0.041					
N	44	44		44	44					
CP	0.102	_		0.004	_					

# F.7 PIC16C7XX Family of Devces

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72 <sup>(1)</sup>
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x14 words)	512	1K	1K	2К	2К	—
Memory	ROM Program Memory (14K words)	_	_	—	_	_	2К
	Data Memory (bytes)	36	36	68	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/ PWM Module(s)	—	_	—	_	1	1
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	—	_	—	_	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C
	Parallel Slave Port	—	—	—	_	—	—
	A/D Converter (8-bit) Channels	4	4	4	4	5	5
	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5
Features	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Oper- ation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	368	368
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Mod- ule(s)	2	2	2	2
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART
	Parallel Slave Port	_	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
Features	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
. outuroo	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.